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(57) **ABSTRACT**

An electronic assembly includes a circuit board assembly and a liquid cold plate. The circuit board assembly includes a board, a first heat-generating component, and a second heat-generating component, where the first heat-generating component and the second heat-generating component are disposed on the board. The liquid cold plate includes a liquid inlet and a liquid outlet. The liquid cold plate includes a first cooling region and a second cooling region, where the second cooling region is closer to the liquid outlet than the first cooling region. A heat dissipation capability of the first cooling region is stronger than that of the second cooling region. A heat-generating density of the first heat-generating component is greater than that of the second heat-generating component, the first heat-generating component is thermally connected to the first cooling region, and the second heat-generating component is thermally connected to the second cooling region.

